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JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

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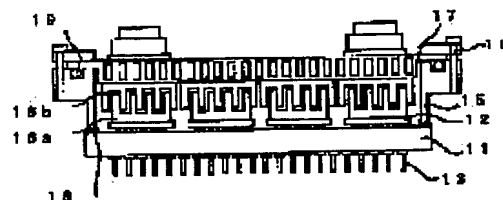
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(54) SEALED COOLING STRUCTURE OF MULTICHIP MODULE

(57)Abstract:

PURPOSE: To provide a sealed cooling structure of a multichip module excellent in high density mounting, high sealed connection reliability, low manufacturing cost and high cooling performance.

CONSTITUTION: One side surface of a frame 15 which is matched with the thermal expansion coefficient of a wiring board 11 is connected with a surface of the wiring board 11 with solder on which surface a semiconductor device 12 is mounted. The other side surface is fixed on a lid member 17 which serves as a heat sink above the wiring board 11, through a packing 19, by using bolt fastening 10 or a means wherein total heating is not used.



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